

國立交通大學

電子工程學系 電子研究所碩士班

碩士論文

共鍍銅鈦金屬在三維接合連線之電性分析及可
靠度測量



Electrical Performance and Reliability Investigation of
Co-sputtered Cu/Ti as 3D Bonded Interconnect

研究生：陳小予

指導教授：陳冠能 博士

中華民國一〇一年八月

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